

ESP32-S2-MINI-2

ESP32-S2-MINI-2U

Datasheet

2.4 GHz Wi-Fi (802.11 b/g/n) module

Built around ESP32-S2 series of SoC, Xtensa® single-core 32-bit LX7 microprocessor

4 MB flash and optional 2 MB PSRAM in chip package

37 GPIOs, rich set of peripherals

On-board PCB antenna or external antenna connector



Version 0.1
Espressif Systems
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1 Module Overview

1.1 Features

CPU and On-Chip Memory

- ESP32-S2FH4 or ESP32-S2FN4R2 embedded, Xtensa® single-core 32-bit LX7 microprocessor, up to 240 MHz
- 128 KB ROM
- 320 KB SRAM
- 16 KB SRAM in RTC
- 4 MB embedded flash
- 2 MB embedded PSRAM (ESP32-S2FN4R2 only)

Wi-Fi

- 802.11 b/g/n
- Bit rate: 802.11n up to 150 Mbps
- A-MPDU and A-MSDU aggregation
- 0.4 μ s guard interval support
- Operating frequency: 2412 ~ 2484 MHz

Peripherals

- GPIO, SPI, LCD, UART, I2C, I2S, Camera interface, IR, pulse counter, LED PWM, TWAI® (compatible with ISO 11898-1, i.e. CAN Specification 2.0), full-speed USB OTG, ADC, DAC, touch sensor, temperature sensor

Integrated Components on Module

- 40 MHz crystal oscillator

Antenna Options

- On-board PCB antenna (ESP32-S2-MINI-2)
- External antenna via a connector (ESP32-S2-MINI-2U)

Operating Conditions

- Operating voltage/Power supply: 3.0 ~ 3.6 V
- Operating ambient temperature:
 - 85 °C version: -40 ~ 85 °C
 - 105 °C version: -40 ~ 105 °C

1.2 Description

ESP32-S2-MINI-2 and ESP32-S2-MINI-2U are two powerful, generic Wi-Fi MCU modules that have a rich set of peripherals. They are an ideal choice for a wide variety of application scenarios related to Internet of Things (IoT), such as wearable electronics and smart home.

The ordering information is as follows:

Table 1: Ordering Information

Module	Ordering code	Chip embedded	Ambient operating temperature (°C)	Module Dimensions (mm)
ESP32-S2-MINI-2 (ANT)	ESP32-S2-MINI-2-N4	ESP32-S2FH4	-40 ~ 85	15.4 × 20.0 × 2.4
	ESP32-S2-MINI-2-H4		-40 ~ 105	
	ESP32-S2-MINI-2-N4R2	ESP32-S2FN4R2	-40 ~ 85	
ESP32-S2-MINI-2U (CONN)	ESP32-S2-MINI-2U-N4	ESP32-S2FH4	-40 ~ 85	15.4 × 15.4 × 2.4
	ESP32-S2-MINI-2U-H4		-40 ~ 105	
	ESP32-S2-MINI-2U-N4R2	ESP32-S2FN4R2	-40 ~ 85	

ESP32-S2-MINI-2 comes with a on-board PCB antenna (ANT), and ESP32-S2-MINI-2U with an external antenna connector (CONN). Both ESP32-S2-MINI-2 and ESP32-S2-MINI-2U have three variants:

- integrating the ESP32-S2FH4 chip (which is embedded with a 4 MB high-temperature flash), and operating at $-40 \sim 85\text{ }^{\circ}\text{C}$
- integrating the ESP32-S2FH4 chip (which is embedded with a 4 MB high-temperature flash), and operating at $-40 \sim 105\text{ }^{\circ}\text{C}$
- integrating the ESP32-S2FN4R2 chip (which is embedded with a 4 MB flash and 2 MB PSRAM), and operating at $-40 \sim 85\text{ }^{\circ}\text{C}$

In this datasheet unless otherwise stated, ESP32-S2-MINI-2 refers to all variants of ESP32-S2-MINI-2, whereas ESP32-S2-MINI-2U refers to all variants of ESP32-S2-MINI-2U.

The ESP32-S2FH4 chip and the ESP32-S2FN4R2 chip falls into the same category, namely ESP32-S2 chip series. ESP32-S2 series of chips has an Xtensa® 32-bit LX7 CPU that operates at up to 240 MHz. It has a low-power co-processor that can be used instead of the CPU to save power while performing tasks that do not require much computing power, such as monitoring of peripherals.

ESP32-S2 series integrates a rich set of peripherals, ranging from SPI, I2S, UART, I2C, LED PWM, TWAI®, LCD, Camera interface, ADC, DAC, touch sensor, temperature sensor, as well as up to 43 GPIOs. It also includes a full-speed USB On-The-Go (OTG) interface to enable USB communication.

The ESP32-S2FH4 chip and the ESP32-S2FN4R2 chip vary in:

- temperature of embedded flash
- whether a PSRAM is embedded

For details, please refer to Section *ESP32-S2 Series Comparison* in [ESP32-S2 Series Datasheet](#).

1.3 Applications

- Generic Low-power IoT Sensor Hub
- Generic Low-power IoT Data Loggers
- Cameras for Video Streaming
- Over-the-top (OTT) Devices
- USB Devices
- Speech Recognition
- Image Recognition
- Mesh Network
- Home Automation
- Smart Home Control Panel
- Smart Building
- Industrial Automation
- Smart Agriculture
- Audio Applications
- Health Care Applications
- Wi-Fi-enabled Toys
- Wearable Electronics
- Retail & Catering Applications
- Smart POS Machines

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2 Block Diagram

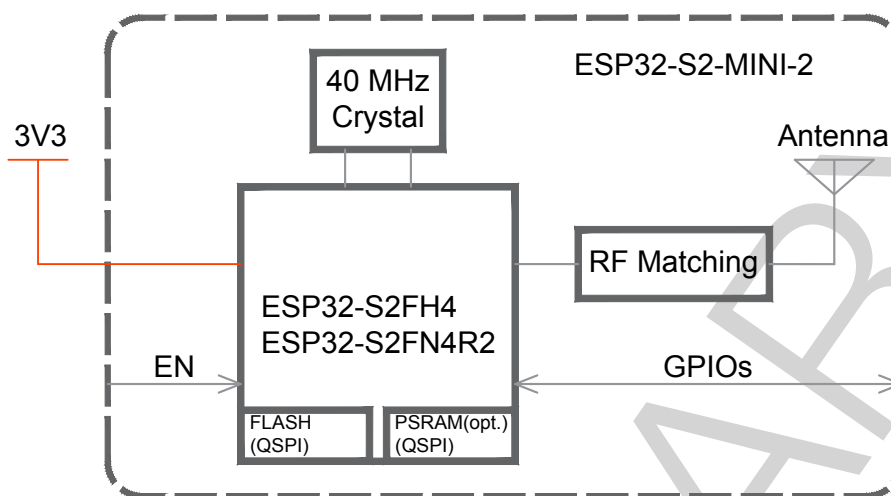


Figure 1: ESP32-S2-MINI-2 Block Diagram

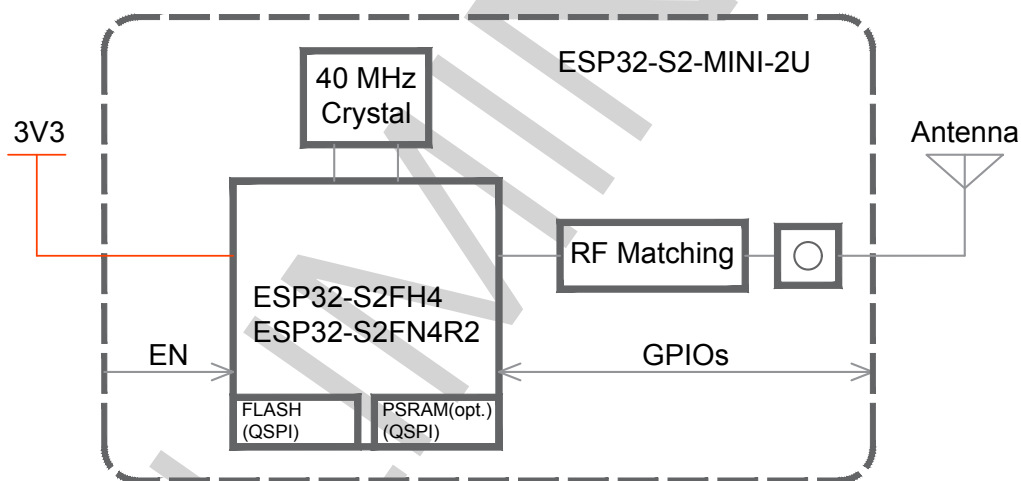


Figure 2: ESP32-S2-MINI-2U Block Diagram

3 Pin Definitions

3.1 Pin Layout

The pin diagram below shows the approximate location of pins on the module. For the actual diagram drawn to scale, please refer to Figure 7.1 *Physical Dimensions*.

The pin layout is applicable for ESP32-S2-MINI-2 and ESP32-S2-MINI-2U, but the latter has no keepout zone.

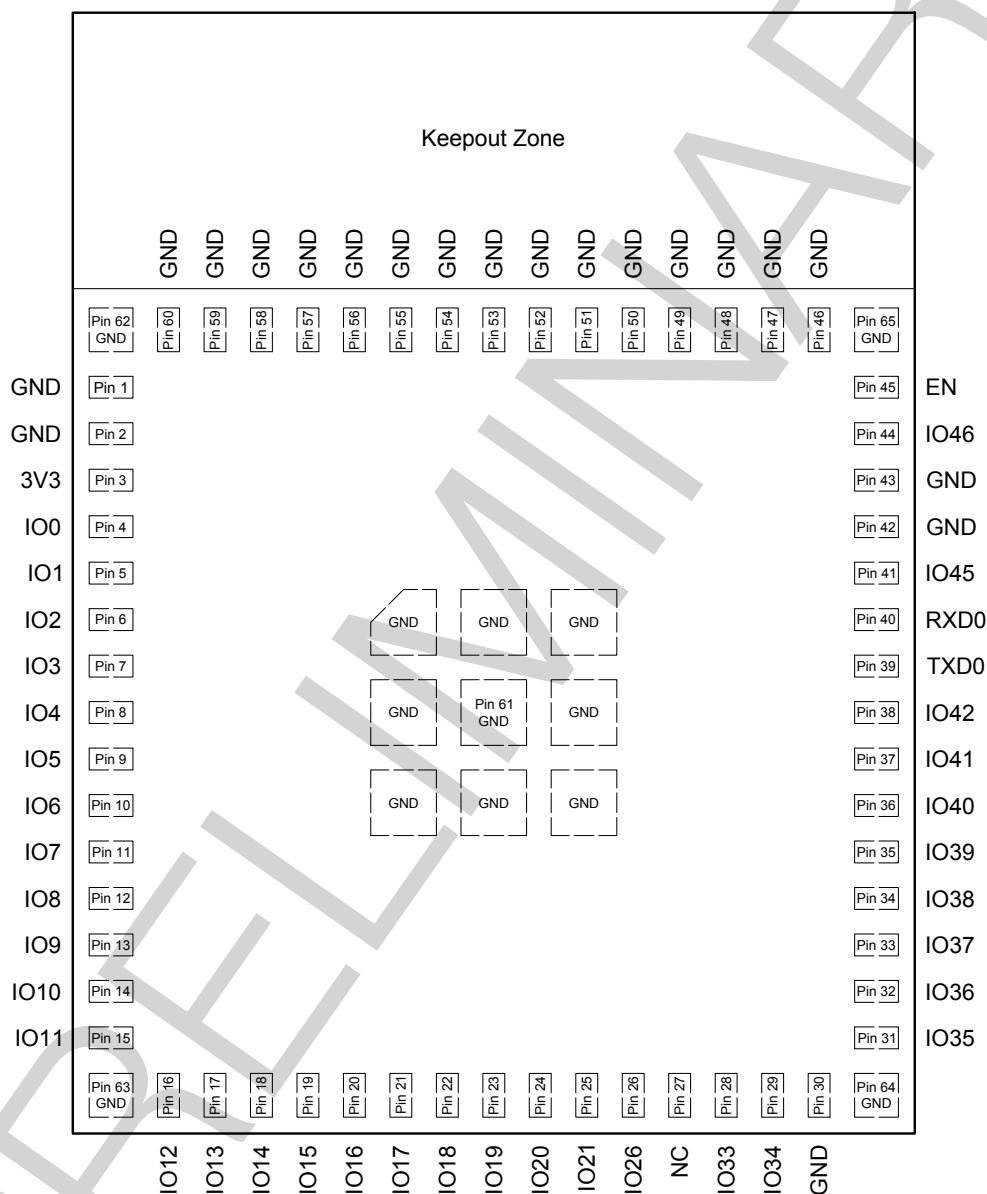


Figure 3: ESP32-S2-MINI-2 Pin Layout (Top View)

3.2 Pin Description

The module has 65 pins. See pin definitions in Table 2.

For peripheral pin configurations, please refer to [ESP32-S2 Series Datasheet](#).

Table 2: Pin Definitions

Name	No.	Type ¹	Function
GND	1, 2, 30, 42, 43, 46-65	P	Ground
3V3	3	P	Power supply
IO0	4	I/O/T	RTC_GPIO0, GPIO0
IO1	5	I/O/T	RTC_GPIO1, GPIO1, TOUCH1, ADC1_CH0
IO2	6	I/O/T	RTC_GPIO2, GPIO2, TOUCH2, ADC1_CH1
IO3	7	I/O/T	RTC_GPIO3, GPIO3, TOUCH3, ADC1_CH2
IO4	8	I/O/T	RTC_GPIO4, GPIO4, TOUCH4, ADC1_CH3
IO5	9	I/O/T	RTC_GPIO5, GPIO5, TOUCH5, ADC1_CH4
IO6	10	I/O/T	RTC_GPIO6, GPIO6, TOUCH6, ADC1_CH5
IO7	11	I/O/T	RTC_GPIO7, GPIO7, TOUCH7, ADC1_CH6
IO8	12	I/O/T	RTC_GPIO8, GPIO8, TOUCH8, ADC1_CH7
IO9	13	I/O/T	RTC_GPIO9, GPIO9, TOUCH9, ADC1_CH8, FSPiHD
IO10	14	I/O/T	RTC_GPIO10, GPIO10, TOUCH10, ADC1_CH9, FSPiCS0, FSPiIO4
IO11	15	I/O/T	RTC_GPIO11, GPIO11, TOUCH11, ADC2_CH0, FSPiD, FSPiIO5
IO12	16	I/O/T	RTC_GPIO12, GPIO12, TOUCH12, ADC2_CH1, FSPiCLK, FSPiIO6
IO13	17	I/O/T	RTC_GPIO13, GPIO13, TOUCH13, ADC2_CH2, FSPiQ, FSPiIO7
IO14	18	I/O/T	RTC_GPIO14, GPIO14, TOUCH14, ADC2_CH3, FSPiWP, FSPiDQS
IO15	19	I/O/T	RTC_GPIO15, GPIO15, U0RTS, ADC2_CH4, XTAL_32K_P
IO16	20	I/O/T	RTC_GPIO16, GPIO16, U0CTS, ADC2_CH5, XTAL_32K_N
IO17	21	I/O/T	RTC_GPIO17, GPIO17, U1TXD, ADC2_CH6, DAC_1
IO18	22	I/O/T	RTC_GPIO18, GPIO18, U1RXD, ADC2_CH7, DAC_2, CLK_OUT3
IO19	23	I/O/T	RTC_GPIO19, GPIO19, U1RTS, ADC2_CH8, CLK_OUT2, USB_D-
IO20	24	I/O/T	RTC_GPIO20, GPIO20, U1CTS, ADC2_CH9, CLK_OUT1, USB_D+
IO21	25	I/O/T	RTC_GPIO21, GPIO21
IO26 ²	26	I/O/T	SPiCS1, GPIO26
NC	27	—	NC
IO33	28	I/O/T	SPiIO4, GPIO33, FSPiHD
IO34	29	I/O/T	SPiIO5, GPIO34, FSPiCS0
IO35	31	I/O/T	SPiIO6, GPIO35, FSPiD
IO36	32	I/O/T	SPiIO7, GPIO36, FSPiCLK
IO37	33	I/O/T	SPiDQS, GPIO37, FSPiQ
IO38	34	I/O/T	GPIO38, FSPiWP
IO39	35	I/O/T	MTCK, GPIO39, CLK_OUT3
IO40	36	I/O/T	MTDO, GPIO40, CLK_OUT2
IO41	37	I/O/T	MTDI, GPIO41, CLK_OUT1
IO42	38	I/O/T	MTMS, GPIO42
TXD0	39	I/O/T	U0TXD, GPIO43, CLK_OUT1
RXD0	40	I/O/T	U0RXD, GPIO44, CLK_OUT2
IO45	41	I/O/T	GPIO45

Cont'd on next page

Table 2 – cont'd from previous page

Name	No.	Type ¹	Function
IO46	44	I	GPIO46
EN	45	I	High: on, enables the chip. Low: off, the chip powers off. Note: Do not leave the EN pin floating.

¹ P: power supply; I: input; O: output; T: high impedance.

² IO26 is used by the embedded PSRAM on the ESP32-S2-MINI-2-N4R2 and ESP32-S2-MINI-2U-N4R2 modules, and cannot be used for other purposes.

3.3 Strapping Pins

Note:

The content below is excerpted from Section Strapping Pins in [ESP32-S2 Series Datasheet](#). For the strapping pin mapping between the chip and modules, please refer to Chapter 5 [Module Schematics](#).

ESP32-S2 has three strapping pins:

- GPIO0
- GPIO45
- GPIO46

Software can read the values of corresponding bits from register "GPIO_STRAPPING".

During the chip's system reset (power-on-reset, RTC watchdog reset, brownout reset, analog super watchdog reset, and crystal clock glitch detection reset), the latches of the strapping pins sample the voltage level as strapping bits of "0" or "1", and hold these bits until the chip is powered down or shut down.

GPIO0, GPIO45 and GPIO46 are connected to the chip's internal weak pull-up/pull-down during the chip reset. Consequently, if they are unconnected or the connected external circuit is high-impedance, the internal weak pull-up/pull-down will determine the default input level of these strapping pins.

To change the strapping bit values, users can apply the external pull-down/pull-up resistances, or use the host MCU's GPIOs to control the voltage level of these pins when powering on ESP32-S2.

After reset, the strapping pins work as normal-function pins.

Refer to Table 3 for a detailed boot-mode configuration of the strapping pins.

Table 3: Strapping Pins

VDD_SPI Voltage ^{1 2}			
Pin	Default	3.3 V	1.8 V
GPIO45	Pull-down	0	1
Bootling Mode ³			
Pin	Default	SPI Boot	Download Boot
GPIO0	Pull-up	1	0
GPIO46	Pull-down	Don't-care	0
Enabling/Disabling ROM Messages Print During Bootling ^{4 5}			
Pin	Default	Enabled	Disabled
GPIO46	Pull-down	See note 5	See note 5

Note:

1. The functionality of strapping pin GPIO45 to select VDD_SPI voltage may be disabled by setting VDD_SPI_FORCE eFuse to 1. In such a case the voltage is selected with eFuse bit VDD_SPI_TIEH.
2. Since ESP32-S2FH2, ESP32-S2FH4, ESP32-S2FN4R2, and ESP32-S2R2 come with both/either 3.3 V SPI flash and/or PSRAM, VDD_SPI must be configured to 3.3 V.
3. The strapping combination of GPIO46 = 1 and GPIO0 = 0 is invalid and will trigger unexpected behavior.

4. ROM code can be printed over U0TXD (by default) or DAC_1, depending on the eFuse bit.
5. When eFuse UART_PRINT_CONTROL value is:
 - 0, print is normal during boot and not controlled by GPIO46.
 - 1 and GPIO46 is 0, print is normal during boot; but if GPIO46 is 1, print is disabled.
 - 2 and GPIO46 is 0, print is disabled; but if GPIO46 is 1, print is normal.
 - 3, print is disabled and not controlled by GPIO46.

4 Electrical Characteristics

The values presented in this section are preliminary and may change with the final release of this datasheet.

4.1 Absolute Maximum Ratings

Stresses above those listed in *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Table 4: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
VDD33	Power supply voltage	−0.3	3.6	V
T _{STORE}	Storage temperature	−40	105	°C

4.2 Recommended Operating Conditions

Table 5: Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VDD33	Power supply voltage	3.0	3.3	3.6	V
I _{VDD}	Current delivered by external power supply	0.5	—	—	A
T _A	Operating ambient temperature	85 °C version	−40	85	°C
		105 °C version		105	

4.3 DC Characteristics (3.3 V, 25 °C)

Table 6: DC Characteristics (3.3 V, 25 °C)

Symbol	Parameter	Min	Typ	Max	Unit
C _{IN}	Pin capacitance	—	2	—	pF
V _{IH}	High-level input voltage	0.75 × VDD ¹	—	VDD ¹ + 0.3	V
V _{IL}	Low-level input voltage	−0.3	—	0.25 × VDD ¹	V
I _{IH}	High-level input current	—	—	50	nA
I _{IL}	Low-level input current	—	—	50	nA
V _{OH} ²	High-level output voltage	0.8 × VDD ¹	—	—	V
V _{OL} ²	Low-level output voltage	—	—	0.1 × VDD ¹	V
I _{OH}	High-level source current (VDD ¹ = 3.3 V, V _{OH} ≥ 2.64 V, PAD_DRIVER = 3)	—	40	—	mA
I _{OL}	Low-level sink current (VDD ¹ = 3.3 V, V _{OL} = 0.495 V, PAD_DRIVER = 3)	—	28	—	mA
R _{PU}	Pull-up resistor	—	45	—	kΩ
R _{PD}	Pull-down resistor	—	45	—	kΩ

V_{IH_nRST}	Chip reset release voltage	$0.75 \times VDD^1$	—	$VDD^1 + 0.3$	V
V_{IL_nRST}	Chip reset voltage	-0.3	—	$0.25 \times VDD^1$	V

¹ VDD is the I/O voltage for pins of a particular power domain.

² V_{OH} and V_{OL} are measured using high-impedance load.

5 Module Schematics

This is the reference design of the module.

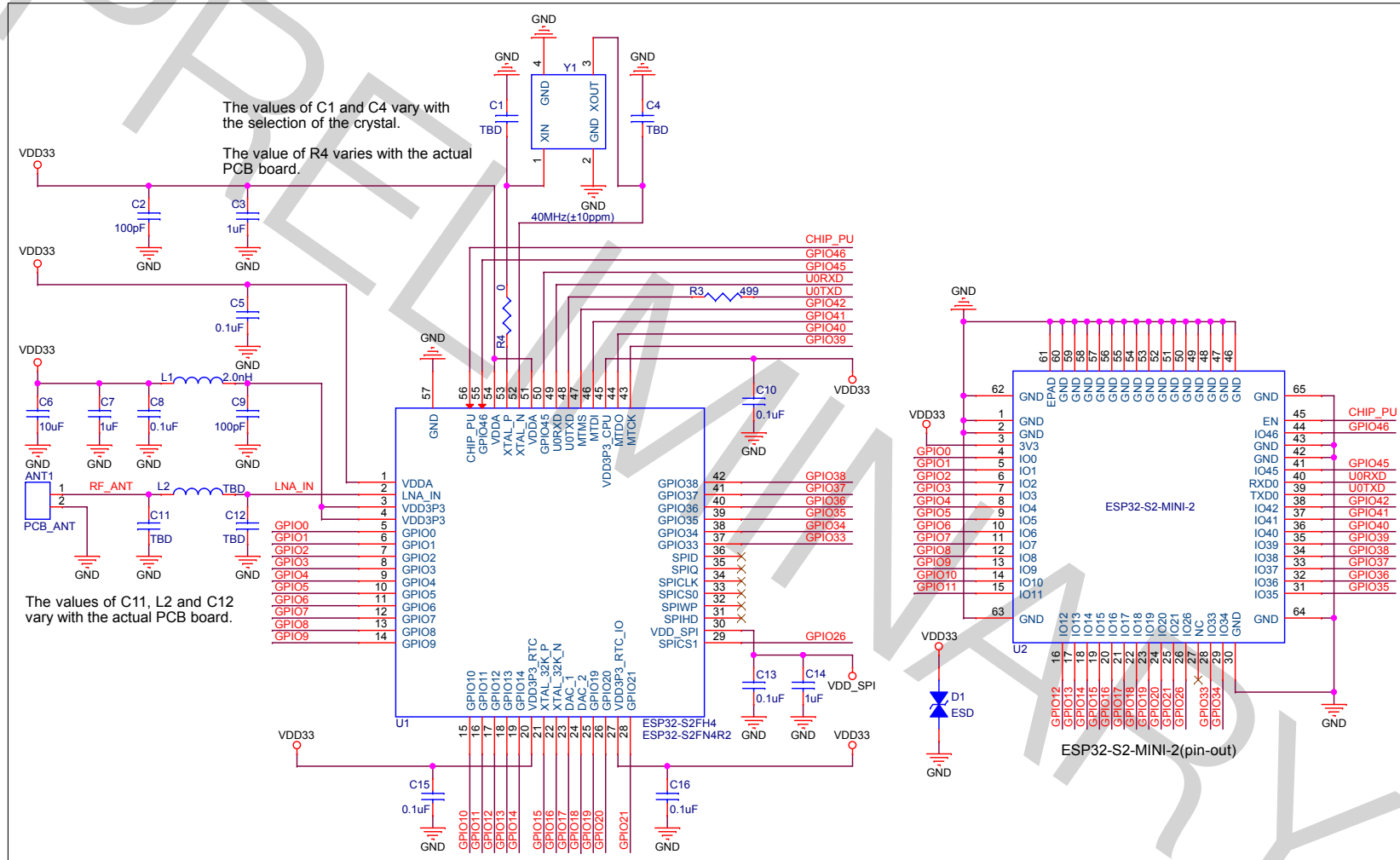


Figure 4: ESP32-S2-MINI-2 Schematics

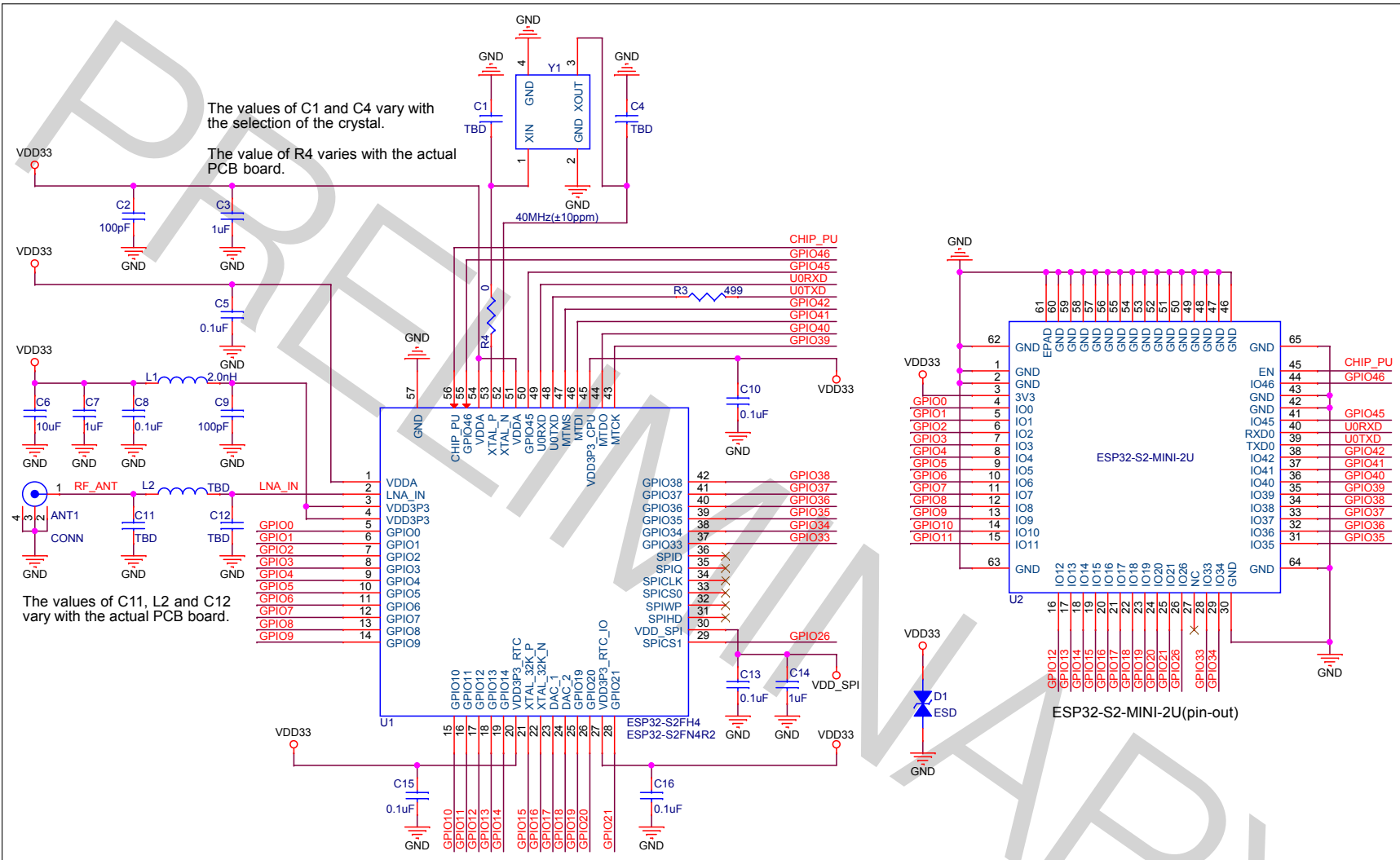


Figure 5: ESP32-S2-MINI-2U Schematics

6 Peripheral Schematics

This is the typical application circuit of the module connected with peripheral components (for example, power supply, antenna, reset button, JTAG interface, and UART interface).

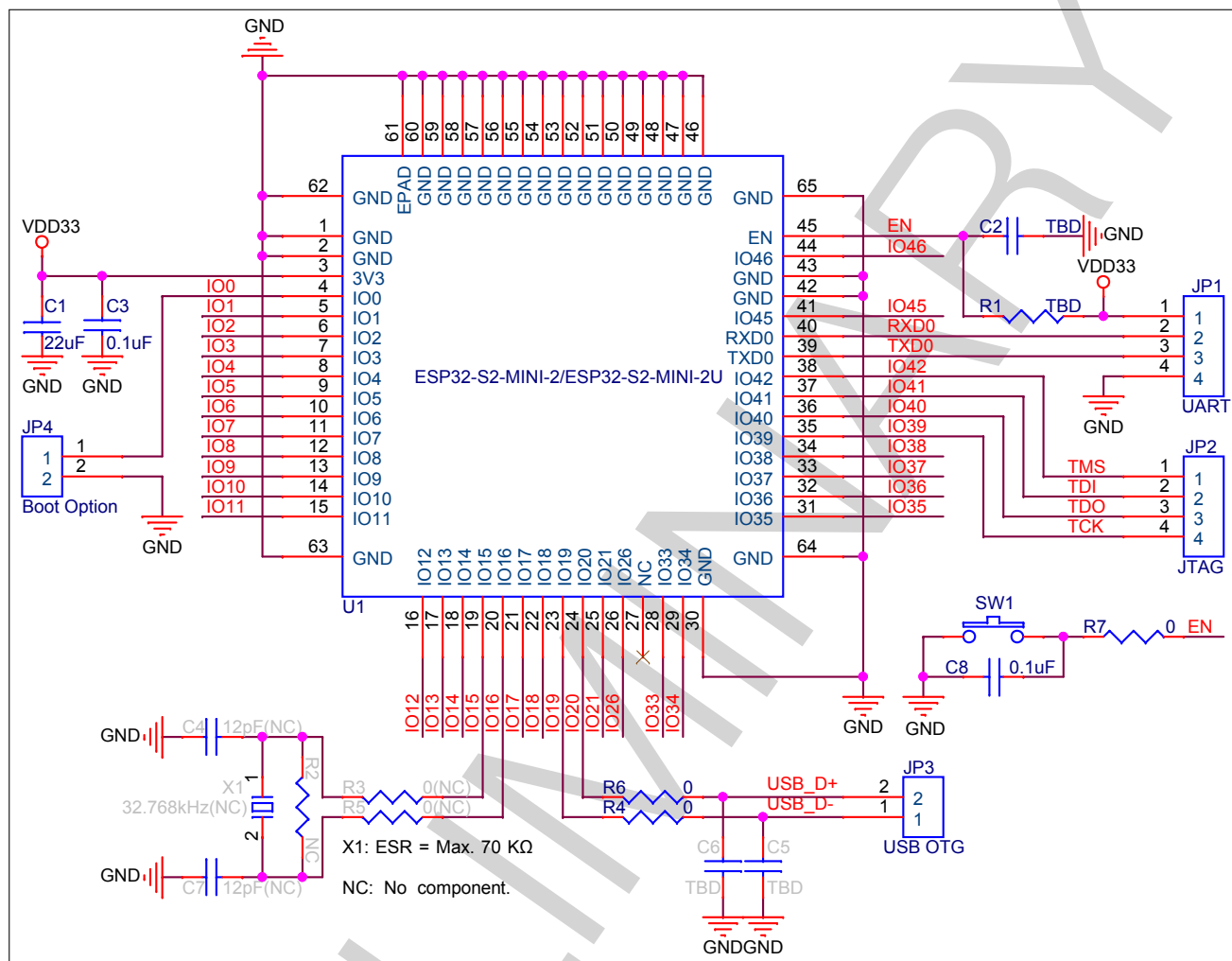


Figure 6: Peripheral Schematics

- Soldering the EPAD to the ground of the base board is not a must, however, it can optimize thermal performance. If you choose to solder it, please apply the correct amount of soldering paste.
- To ensure that the power supply to the ESP32-S2 chip is stable during power-up, it is advised to add an RC delay circuit at the EN pin. The recommended setting for the RC delay circuit is usually $R = 10\text{ k}\Omega$ and $C = 1\text{ }\mu\text{F}$. However, specific parameters should be adjusted based on the power-up timing of the module and the power-up and reset sequence timing of the chip. For ESP32-S2's power-up and reset sequence timing diagram, please refer to Section *Power Scheme* in [ESP32-S2 Series Datasheet](#).

7 Physical Dimensions and PCB Land Pattern

7.1 Physical Dimensions

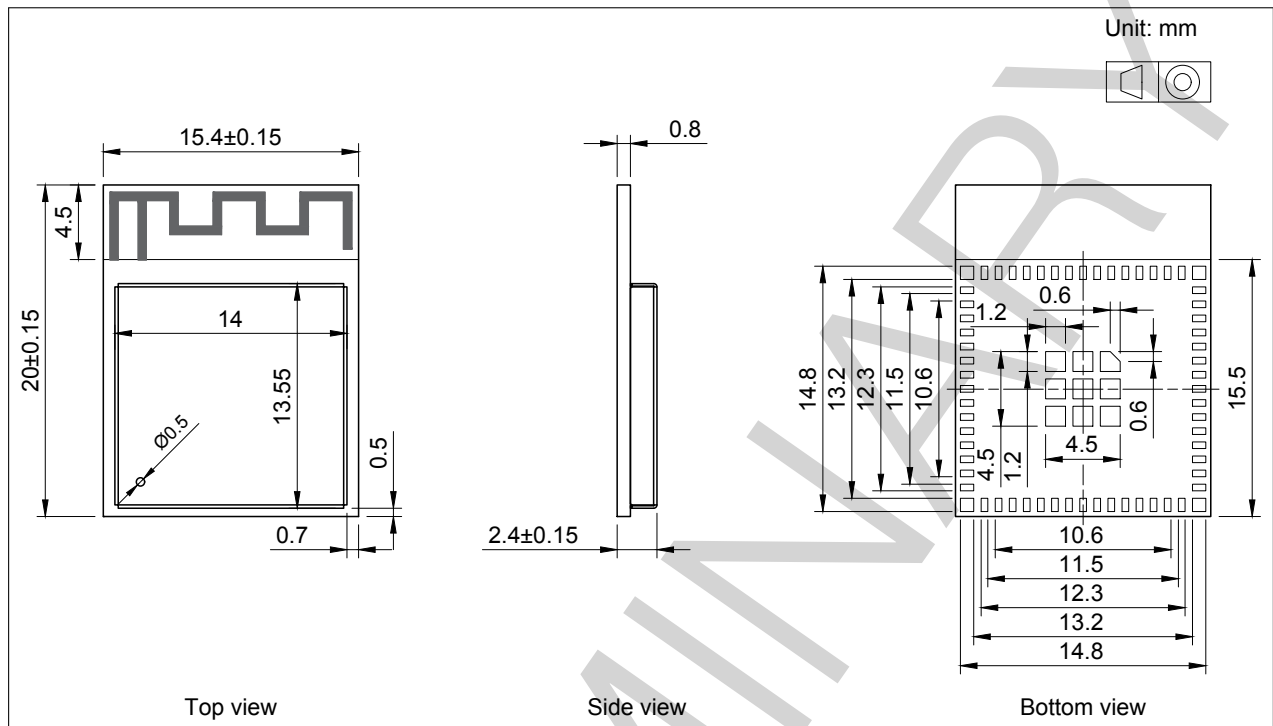


Figure 7: ESP32-S2-MINI-2 Physical Dimensions

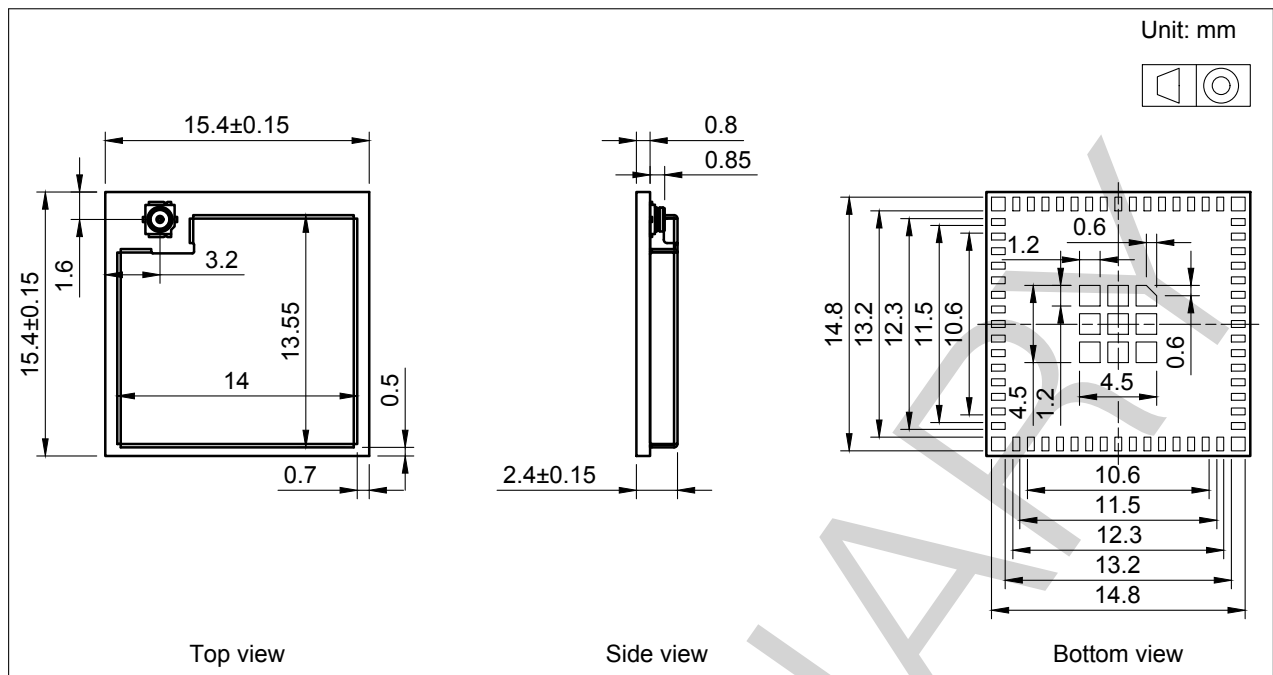


Figure 8: ESP32-S2-MINI-2U Physical Dimensions

Note:

For information about tape, reel, and product marking, please refer to [Espressif Module Package Information](#).

7.2 Recommended PCB Land Pattern

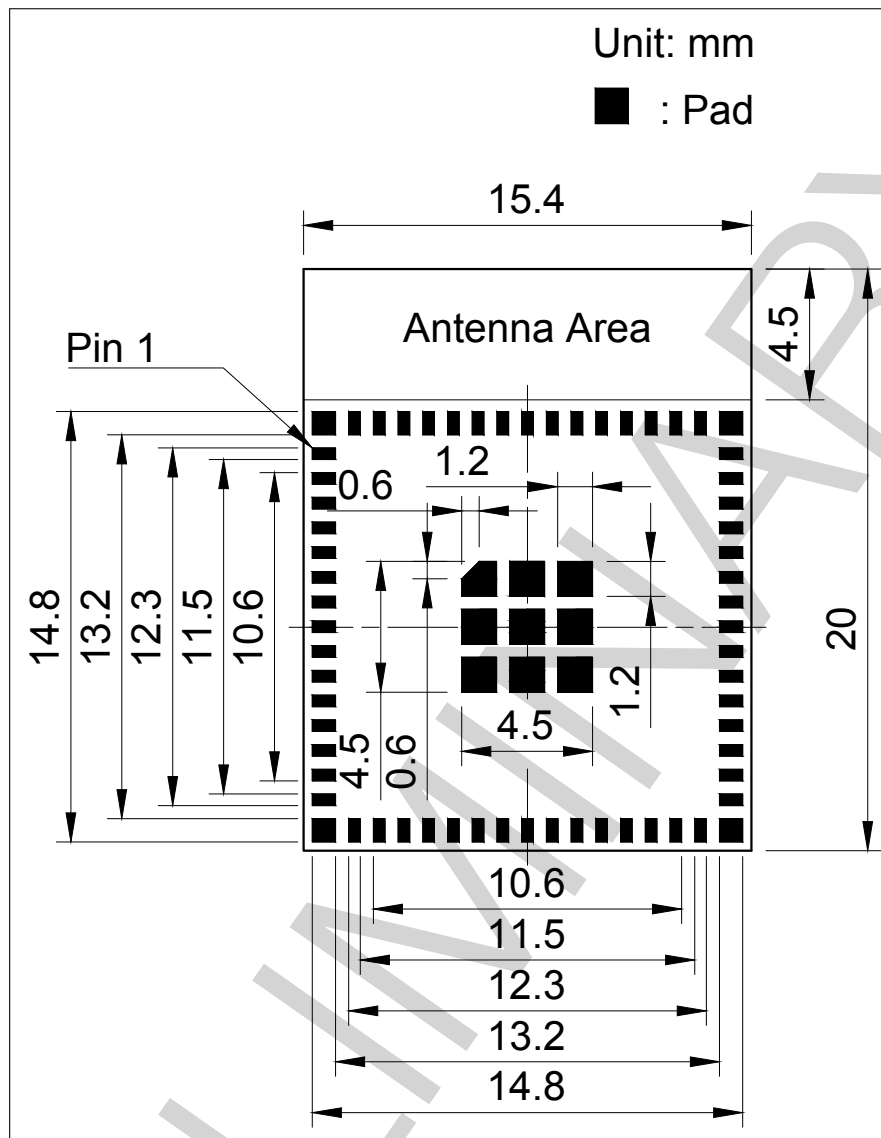


Figure 9: ESP32-S2-MINI-2 Recommended PCB Land Pattern

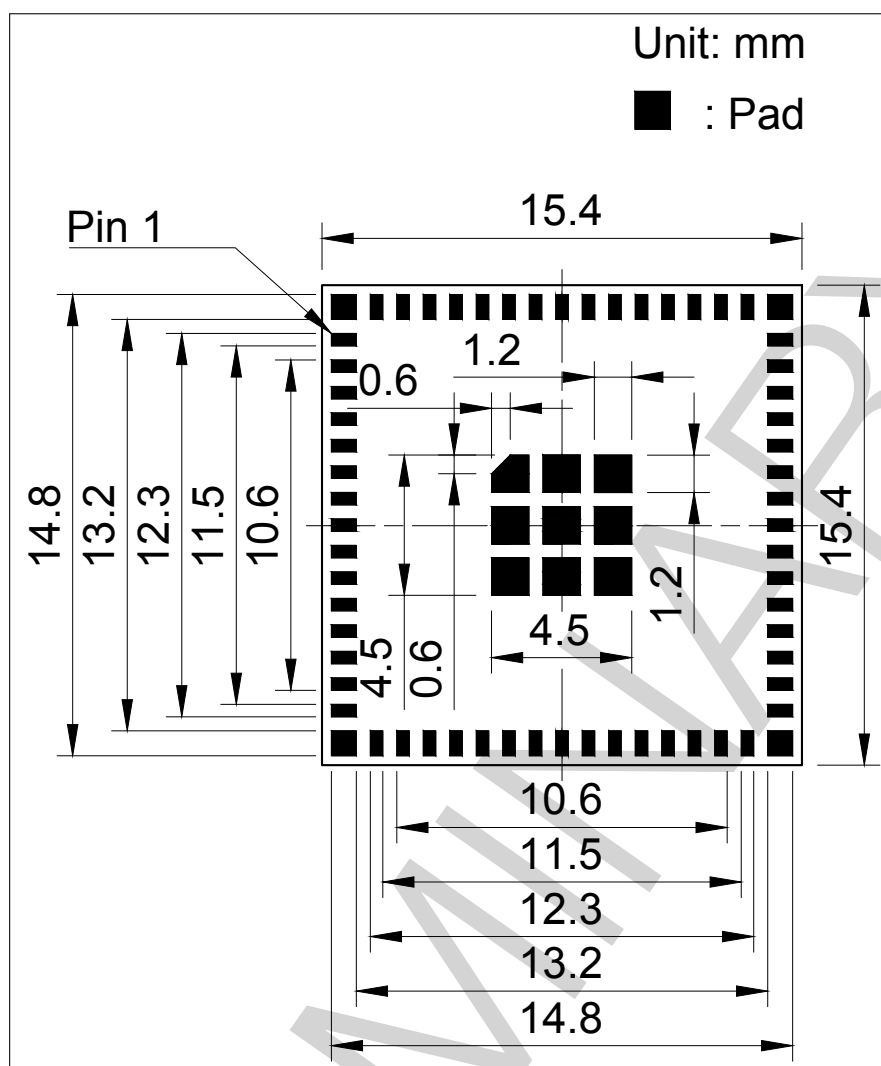


Figure 10: ESP32-S2-MINI-2U Recommended PCB Land Pattern

7.3 Dimensions of External Antenna Connector

ESP32-S2-MINI-2U uses the third generation external antenna connector as shown in Figure 11. This connector is compatible with the following connectors:

- W.FL Series connector from Hirose
- MHF III connector from I-PEX
- AMMC connector from Amphenol

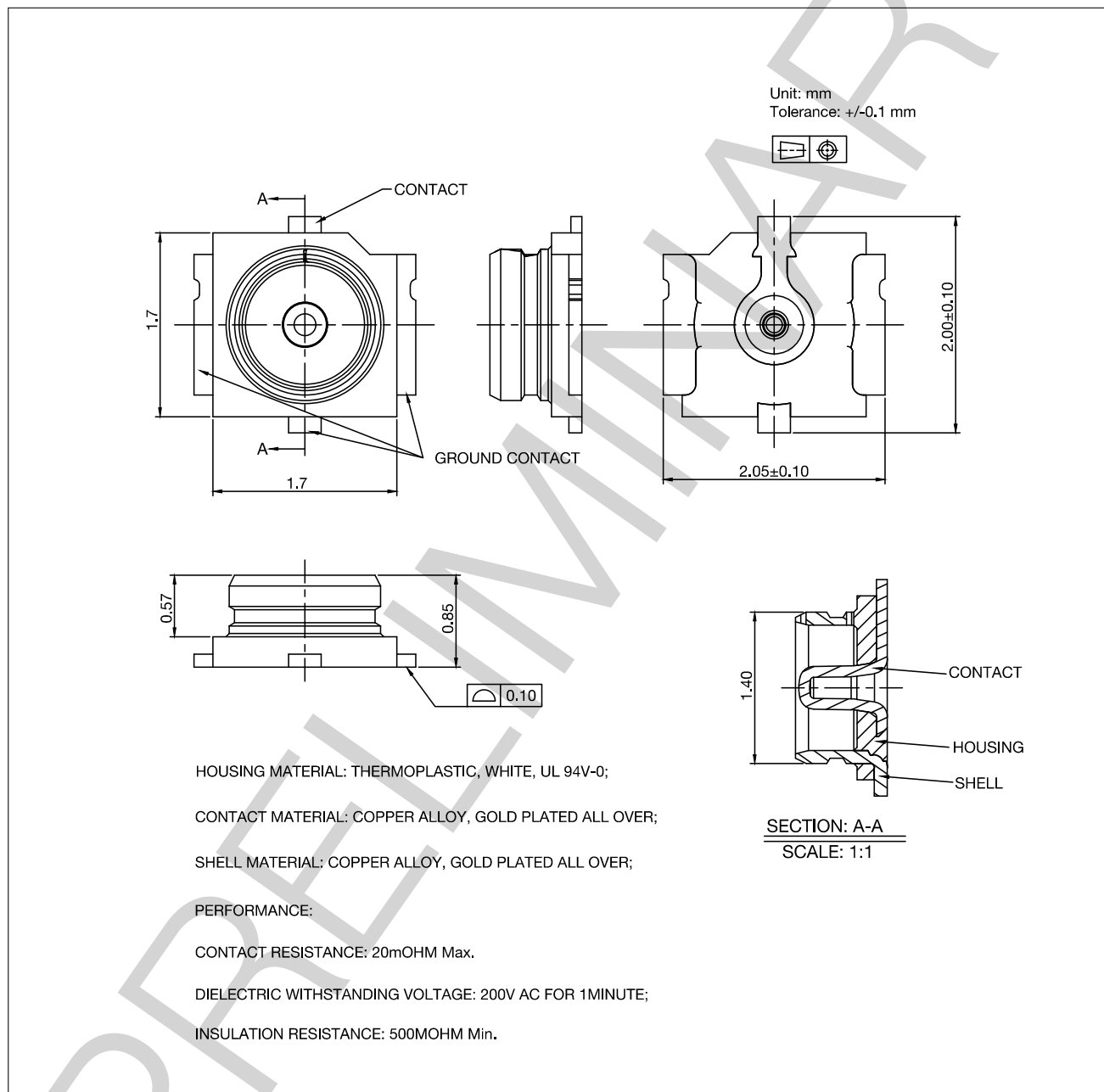


Figure 11: Dimensions of External Antenna Connector

8 Product Handling

8.1 Storage Conditions

The products sealed in moisture barrier bags (MBB) should be stored in a non-condensing atmospheric environment of $< 40\text{ }^{\circ}\text{C}$ and $/90\%\text{RH}$. The module is rated at the moisture sensitivity level (MSL) of 3.

After unpacking, the module must be soldered within 168 hours with the factory conditions $25\pm 5\text{ }^{\circ}\text{C}$ and $/60\%\text{RH}$. If the above conditions are not met, the module needs to be baked.

8.2 Electrostatic Discharge (ESD)

- Human body model (HBM): $\pm 2000\text{ V}$
- Charged-device model (CDM): $\pm 500\text{ V}$
- Air discharge: $\pm 6000\text{ V}$
- Contact discharge: $\pm 4000\text{ V}$

8.3 Reflow Profile

Solder the module in a single reflow.

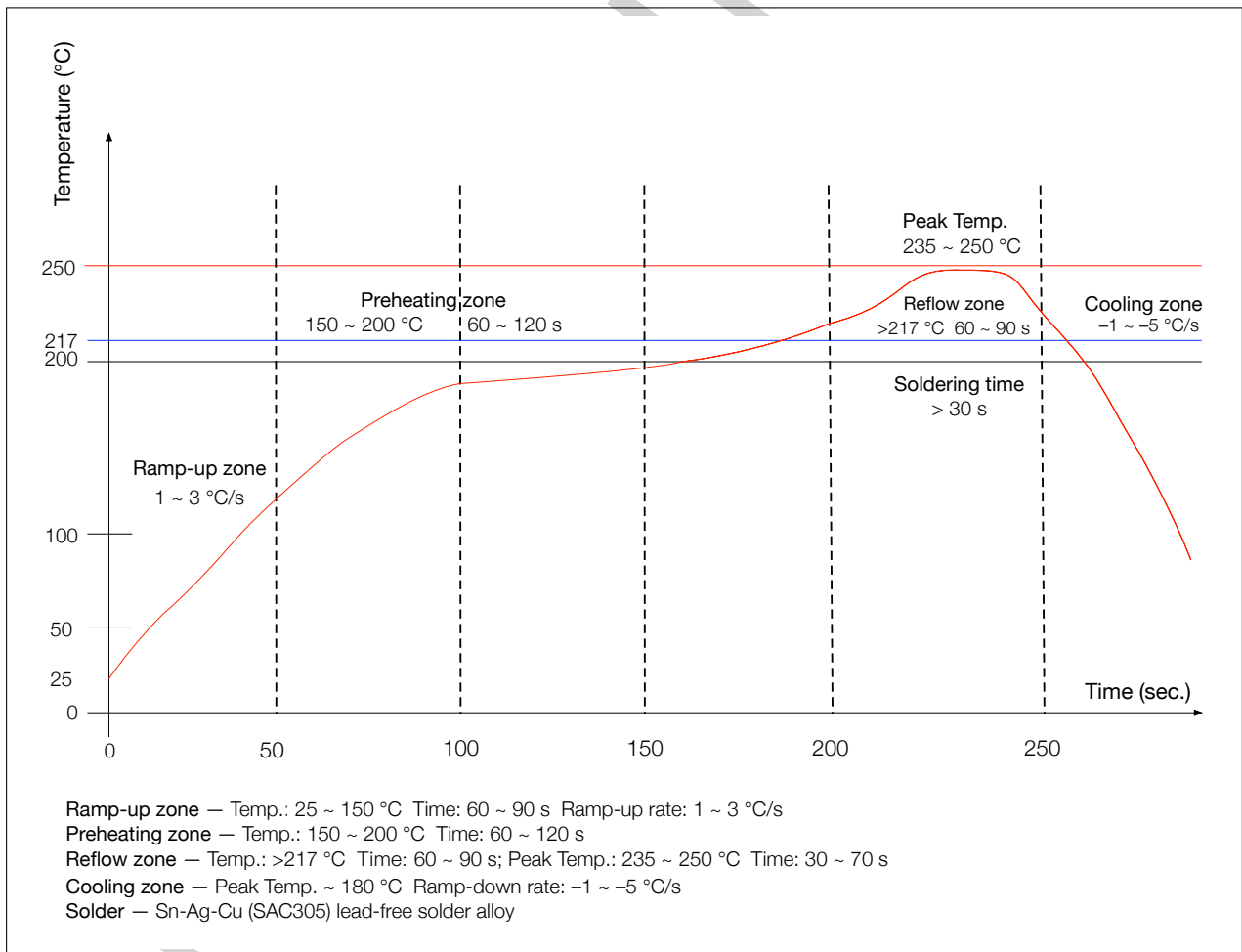


Figure 12: Reflow Profile

9 Related Documentation and Resources

Related Documentation

- [ESP32-S2 Series Datasheet](#) – Specifications of the ESP32-S2 hardware.
- [ESP32-S2 Technical Reference Manual](#) – Detailed information on how to use the ESP32-S2 memory and peripherals.
- [ESP32-S2 Hardware Design Guidelines](#) – Guidelines on how to integrate the ESP32-S2 into your hardware product.
- *Certificates*
<https://espressif.com/en/support/documents/certificates>
- *ESP32-S2 Product/Process Change Notifications (PCN)*
<https://espressif.com/en/support/documents/pcns>
- *ESP32-S2 Advisories* – Information on security, bugs, compatibility, component reliability.
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Developer Zone

- [ESP-IDF Programming Guide for ESP32-S2](#) – Extensive documentation for the ESP-IDF development framework.
- *ESP-IDF* and other development frameworks on GitHub.
<https://github.com/espressif>
- *ESP32 BBS Forum* – Engineer-to-Engineer (E2E) Community for Espressif products where you can post questions, share knowledge, explore ideas, and help solve problems with fellow engineers.
<https://esp32.com/>
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Products

- *ESP32-S2 Series SoCs* – Browse through all ESP32-S2 SoCs.
<https://espressif.com/en/products/socs?id=ESP32-S2>
- *ESP32-S2 Series Modules* – Browse through all ESP32-S2-based modules.
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Revision History

Date	Version	Release notes
2022-01-26	v0.1	Draft.

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